ABSTRACT OF THE DISCLOSURE

CARRIER FILM AND INTEGRATED CIRCUIT DEVICE USING THE SAME AND METHOD OF MAKING THE SAME

A film, on which external electrodes and wire leads are disposed, is divided into two regions. A first region in which an integrated circuit element is disposed and a second region external to the first region. Connection holes are provided in a border area between the first and second regions for connecting the integrated circuit element and electrodes. External electrodes are provided on the first and second regions for connecting to an external substrate. The external electrodes are disposed to form a common matrix. When connecting external electrodes to an external substrate, connections to the external substrate are made in a region corresponding to an integrated circuit element.

FIGURE 1